# **Dual General Purpose Transistor**

# NST3904DXV6T1G, NSVT3904DXV6T1G, NST3904DXV6T5G

The NST/NSV3904DXV6 device is a spin-off of our popular SOT-23/SOT-323 three-leaded device. It is designed for general purpose amplifier applications and is housed in the SOT-563 six-leaded surface mount package. By putting two discrete devices in one package, this device is ideal for low-power surface mount applications where board space is at a premium.

### **Features**

- h<sub>FE</sub>, 100-300
- Low  $V_{CE(sat)}$ ,  $\leq 0.4 \text{ V}$
- Simplifies Circuit Design
- Reduces Board Space
- Reduces Component Count
- AEC-Q101 Qualified and PPAP Capable NSVT3904DXV6T1G
- NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements

### **MAXIMUM RATINGS**

Rating		Symbol	Value	Unit
Collector - Emitter Voltage		$V_{CEO}$	40	Vdc
Collector - Base Voltage		V <sub>CBO</sub>	60	Vdc
Emitter - Base Voltage		V <sub>EBO</sub>	6.0	Vdc
Collector Current - Continuous		I <sub>C</sub>	200	mAdc
Electrostatic Discharge	HBM MM	ESD	>16000 >2000	V

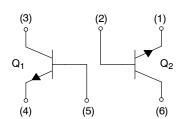
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

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NST/NSV3904DXV6

## MARKING DIAGRAM



SOT-563 CASE 463A STYLE 1



MA = Device Code

M = Date Code

■ = Pb-Free Package

(Note: Microdot may be in either location)

# **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
NST3904DXV6T1G	SOT-563 (Pb-Free)	4000/Tape & Reel
NSVT3904DXV6T1G	SOT-563 (Pb-Free)	4000/Tape & Reel
NST3904DXV6T5G	SOT-563 (Pb-Free)	8000/Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

# THERMAL CHARACTERISTICS

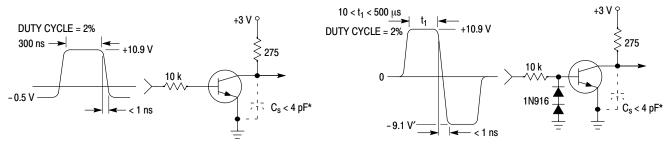
Characteristic (One Junction Heated)	Symbol	Max	Unit
Total Device Dissipation T <sub>A</sub> = 25°C Derate above 25°C (Note 1)	P <sub>D</sub>	357 2.9	mW mW/°C
Thermal Resistance Junction-to-Ambient (Note 1)	$R_{ hetaJA}$	350	°C/W
Characteristic (Both Junctions Heated)	Symbol	Max	Unit
Total Device Dissipation T <sub>A</sub> = 25°C Derate above 25°C (Note 1)	P <sub>D</sub>	500 4.0	mW mW/°C
Thermal Resistance, Junction-to-Ambient (Note 1)	$R_{ heta JA}$	250	°C/W
Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C

<sup>1.</sup> FR-4 @ Minimum Pad

## ELECTRICAL CHARACTERISTICS (T<sub>A</sub> = 25°C unless otherwise noted)

	Characteristic	Symbol	Min	Max	Unit	
OFF CHARACTERISTICS						
Collector - Emitter Breakdown Vo	oltage (Note 2) (I <sub>C</sub> = 1.0 mAdc, I <sub>B</sub> = 0)	V <sub>(BR)CEO</sub>	40	-	Vdc	
Collector - Base Breakdown Volta	V <sub>(BR)CBO</sub>	60	-	Vdc		
Emitter – Base Breakdown Voltag	ge (I <sub>E</sub> = 10 μAdc, I <sub>C</sub> = 0)	V <sub>(BR)EBO</sub>	6.0	-	Vdc	
Base Cutoff Current (V <sub>CE</sub> = 30 V	dc, V <sub>EB</sub> = 3.0 Vdc)	I <sub>BL</sub>	_	50	nAdc	
Collector Cutoff Current (V <sub>CE</sub> = 3	30 Vdc, V <sub>EB</sub> = 3.0 Vdc)	I <sub>CEX</sub>	-	50	nAdc	
ON CHARACTERISTICS (Note 2	2)		•		•	
DC Current Gain $ \begin{array}{l} (I_{C}=0.1 \text{ mAdc, } V_{CE}=1.0 \text{ Vd} \\ (I_{C}=1.0 \text{ mAdc, } V_{CE}=1.0 \text{ Vd} \\ (I_{C}=10 \text{ mAdc, } V_{CE}=1.0 \text{ Vd} \\ (I_{C}=50 \text{ mAdc, } V_{CE}=1.0 \text{ Vd} \\ (I_{C}=100 \text{ mAdc, } V_{CE}=1.0 \text{ Vd} \\ \end{array} $	c) c) c)	h <sub>FE</sub>	40 70 100 60 30	- 300 - -	-	
	s)	V <sub>CE(sat)</sub>	- -	0.2 0.3	Vdc	
Base – Emitter Saturation Voltage ( $I_C = 10 \text{ mAdc}$ , $I_B = 1.0 \text{ mAdc}$ ( $I_C = 50 \text{ mAdc}$ , $I_B = 5.0 \text{ mAdc}$	V <sub>BE(sat)</sub>	0.65	0.85 0.95	Vdc		
SMALL-SIGNAL CHARACTER	ISTICS	<u>.</u>				
Current - Gain - Bandwidth Prod	uct (I <sub>C</sub> = 10 mAdc, V <sub>CE</sub> = 20 Vdc, f = 100 MHz)	f <sub>T</sub>	300	-	MHz	
Output Capacitance (V <sub>CB</sub> = 5.0 Vdc, I <sub>E</sub> = 0, f = 1.0 MHz)		C <sub>obo</sub>	_	4.0	pF	
Input Capacitance (V <sub>EB</sub> = 0.5 Vd	lc, I <sub>C</sub> = 0, f = 1.0 MHz)	C <sub>ibo</sub>	_	8.0	pF	
Input Impedance (V <sub>CE</sub> = 10 Vdc,	h <sub>ie</sub>	1.0 2.0	10 12	kΩ		
Voltage Feedback Ratio (V <sub>CE</sub> = -	h <sub>re</sub>	0.5 0.1	8.0 10	X 10 <sup>-4</sup>		
Small – Signal Current Gain (V <sub>CE</sub> = 10 Vdc, I <sub>C</sub> = 1.0 mAdc, f = 1.0 kHz)		h <sub>fe</sub>	100 100	400 400	-	
Output Admittance ( $V_{CE} = 10 \text{ Vdc}$ , $I_{C} = 1.0 \text{ mAdc}$ , $f = 1.0 \text{ kHz}$ )		h <sub>oe</sub>	1.0 3.0	40 60	μmhos	
Noise Figure (V <sub>CE</sub> = 5.0 Vdc, I <sub>C</sub> = 100 $\mu$ Adc, R <sub>S</sub> = 1.0 k $\Omega$ , f = 1.0 kHz)		NF	_ _	5.0 4.0	dB	
SWITCHING CHARACTERISTIC	CS	1	1			
Delay Time	$(V_{CC} = 3.0 \text{ Vdc}, V_{BE} = -0.5 \text{ Vdc})$	t <sub>d</sub>	_	35		
Rise Time	(I <sub>C</sub> = 10 mAdc, I <sub>B1</sub> = 1.0 mAdc)	t <sub>r</sub>	_	35	ns	
Storage Time	$(V_{CC} = 3.0 \text{ Vdc}, I_{C} = 10 \text{ mAdc})$	t <sub>s</sub>	_	200		
Fall Time	$(I_{B1} = I_{B2} = 1.0 \text{ mAdc})$	t <sub>f</sub>	_	- 50 ns		
	· · ·	•	•	•		

<sup>2.</sup> Pulse Test: Pulse Width  $\leq$  300  $\mu$ s; Duty Cycle  $\leq$  2.0%.

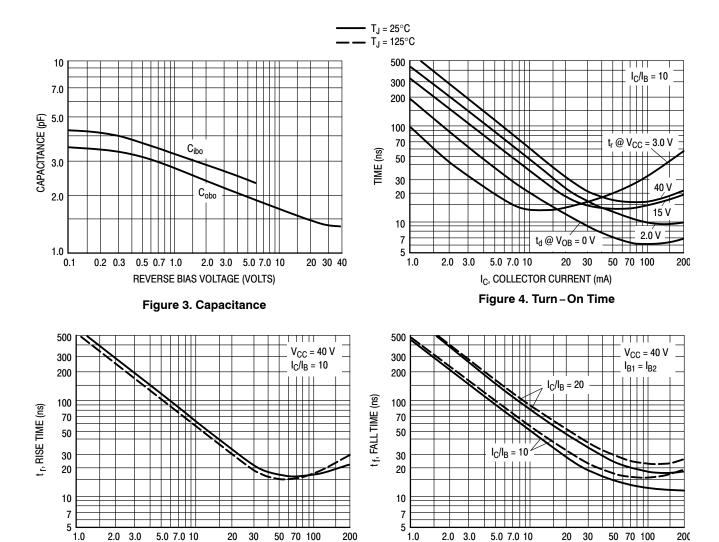


\* Total shunt capacitance of test jig and connectors

Figure 1. Delay and Rise Time Equivalent Test Circuit

Figure 2. Storage and Fall Time Equivalent Test Circuit

## **TYPICAL TRANSIENT CHARACTERISTICS**



I<sub>C</sub>, COLLECTOR CURRENT (mA)

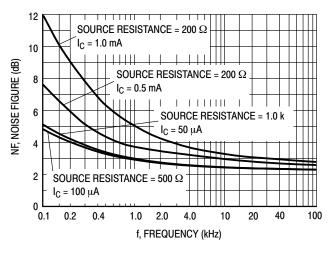
Figure 5. Rise Time

Figure 6. Fall Time

I<sub>C</sub>, COLLECTOR CURRENT (mA)

# TYPICAL AUDIO SMALL-SIGNAL CHARACTERISTICS NOISE FIGURE VARIATIONS

 $(V_{CE} = 5.0 \text{ Vdc}, T_A = 25^{\circ}\text{C}, Bandwidth = 1.0 \text{ Hz})$ 



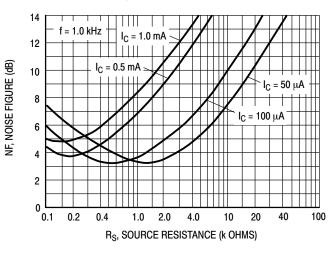
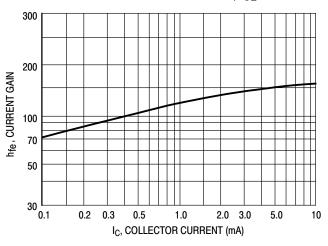


Figure 7. Noise Figure

Figure 8. Noise Figure

### **h PARAMETERS**

 $(V_{CE} = 10 \text{ Vdc}, f = 1.0 \text{ kHz}, T_A = 25^{\circ}\text{C})$ 



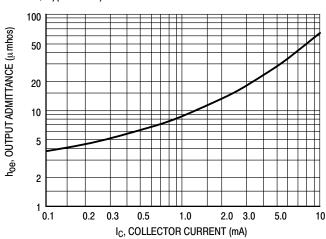


Figure 9. Current Gain

Figure 10. Output Admittance

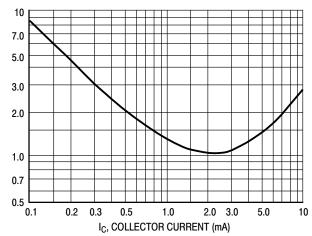


Figure 11. Input Impedance

Figure 12. Voltage Feedback Ratio

, VOLTAGE FEEDBACK RATIO (x 10 -4)

## **TYPICAL STATIC CHARACTERISTICS**

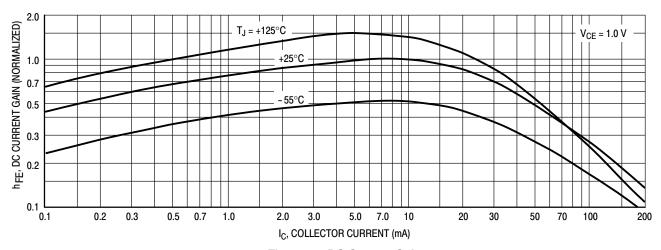


Figure 13. DC Current Gain

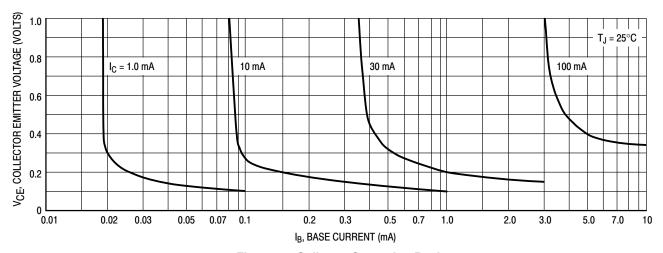


Figure 14. Collector Saturation Region

### **TYPICAL STATIC CHARACTERISTICS**

1.2

 $I_C/I_B = 10$ 

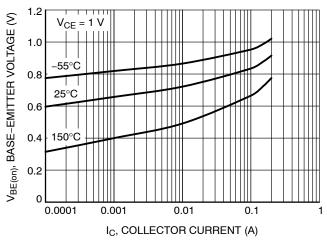
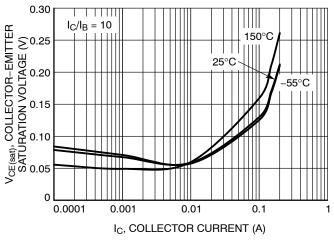


Figure 15. Base Emitter Voltage vs. Collector Current

Figure 16. Base Emitter Saturation Voltage vs.
Collector Current



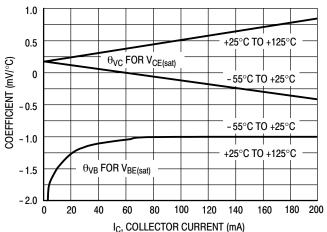


Figure 17. Collector Emitter Saturation Voltage vs. Collector Current

Figure 18. Temperature Coefficients

# MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS



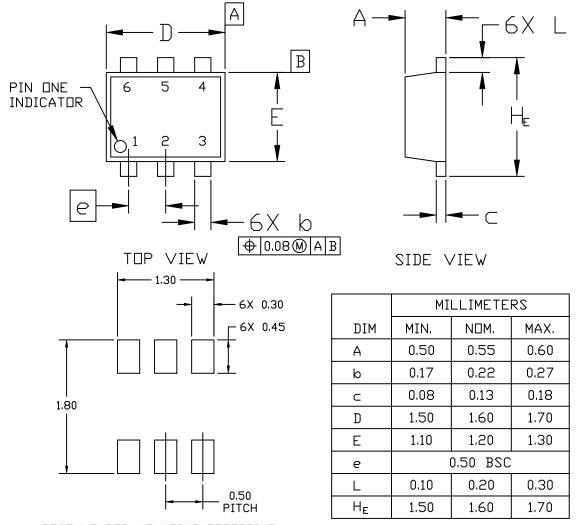


### SOT-563, 6 LEAD CASE 463A ISSUE H

**DATE 26 JAN 2021** 

#### NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.



### RECOMMENDED MOUNTING FOOTPRINT\*

For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SDLDERRM/D.

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## **SOT-563, 6 LEAD**

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**DATE 26 JAN 2021** 

STYLE 1: PIN 1. EMITTER 1 2. BASE 1 3. COLLECTOR 2 4. EMITTER 2 5. BASE 2 6. COLLECTOR 1	STYLE 2: PIN 1. EMITTER 1 2. EMITTER 2 3. BASE 2 4. COLLECTOR 2 5. BASE 1 6. COLLECTOR 1	STYLE 3: PIN 1. CATHODE 1 2. CATHODE 1 3. ANODE/ANODE 4. CATHODE 2 5. CATHODE 2 6. ANODE/ANODE
STYLE 4: PIN 1. COLLECTOR 2. COLLECTOR 3. BASE 4. EMITTER 5. COLLECTOR 6. COLLECTOR	STYLE 5: PIN 1. CATHODE 2. CATHODE 3. ANODE 4. ANODE 5. CATHODE 6. CATHODE	STYLE 6: PIN 1. CATHODE 2. ANODE 3. CATHODE 4. CATHODE 5. CATHODE 6. CATHODE
STYLE 7: PIN 1. CATHODE 2. ANODE 3. CATHODE 4. CATHODE 5. ANODE 6. CATHODE	STYLE 8: PIN 1. DRAIN 2. DRAIN 3. GATE 4. SDURCE 5. DRAIN 6. DRAIN	STYLE 9: PIN 1. SDURCE 1 2. GATE 1 3. DRAIN 2 4. SDURCE 2 5. GATE 2 6. DRAIN 1
STYLE 10: PIN 1. CATHODE 1 2. N/C 3. CATHODE 2 4. ANODE 2 5. N/C 6. ANODE 1	STYLE 11: PIN 1. EMITTER 2 2. BASE 2 3. COLLECTOR 1 4. EMITTER 1 5. BASE 1 6. COLLECTOR 2	

# GENERIC MARKING DIAGRAM\*



XX = Specific Device CodeM = Month Code= Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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